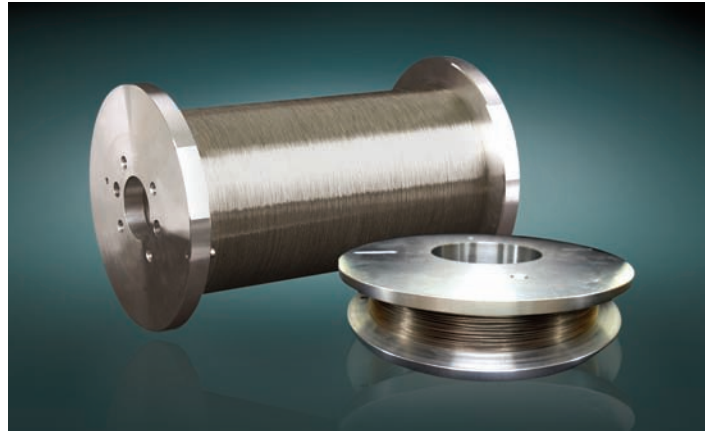
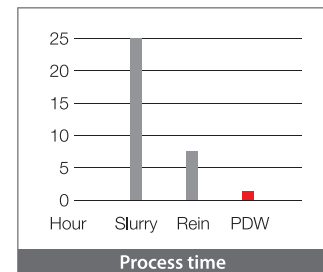
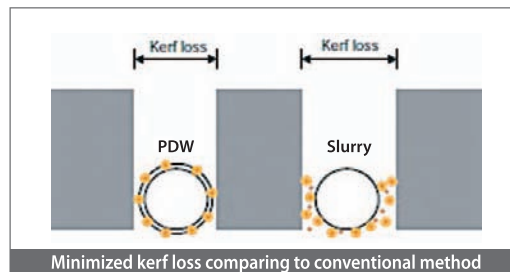


## PRECISION DIAMOND WIRE (PDW)

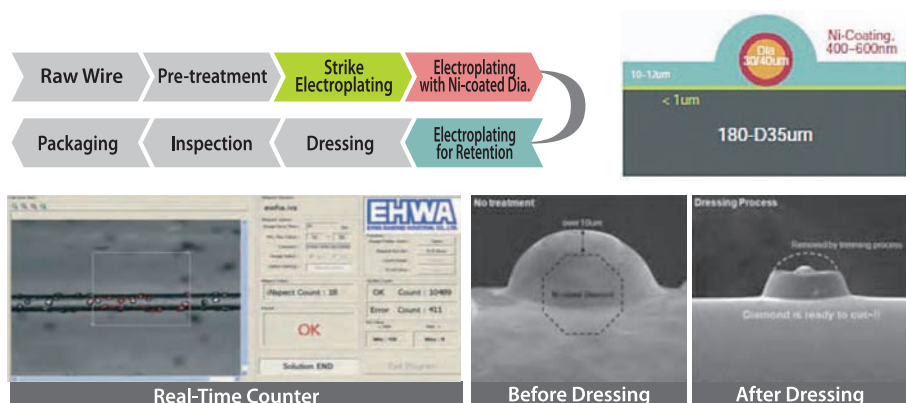


### Advantages

- **High throughput & Superior cutting quality**
  - Reduced process lead time and kerf loss
  - Enhanced flatness of cut materials and superior warp, TTV and Bow values
- **Applicable for thin wafer slicing** - Through uniform diamond grit
- **Longer wire lifetime** - Excellent diamond retention & no wire breakage
- **Faster cutting speed** - 3~10 times compared with slurry process
- **Low cost and eco-friendly** - Slurry free process



### Manufacturing Process



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## SPECS for PDW

|                                   | Core Material <sup>1)</sup> |                  |                       | Diamond Size (μm) | Kerf Loss (μm) |
|-----------------------------------|-----------------------------|------------------|-----------------------|-------------------|----------------|
|                                   | Order Code                  | Diameter (Φ, μm) | WBS (N) <sup>2)</sup> |                   |                |
| Mono-/Poly-Si<br>Wafering         | 60-D10                      | 60               | 12                    | 6~12              | 75~85          |
|                                   | 70-D10                      | 70               | 16                    | 8~12              | 85~95          |
|                                   | 80-D10                      | 80               | 20                    | 8~12              | 90~100         |
| Sapphire Ingot<br>Wafering        | 160-D35                     | 160              | 65                    | 30~40             | 220~240        |
|                                   | 180-D35                     | 180              | 85                    | 30~40             | 235~255        |
|                                   | 180-D45                     | 180              | 85                    | 40~50             | 245~255        |
| Si Squaring/<br>Sapphire Cropping | 250-D45                     | 250              | 180                   | 40~50             | 345~355        |
|                                   | 300-D45                     | 300              | 240                   | 40~50             | 395~405        |
|                                   | 350-D45                     | 300              | 320                   | 40~50             | 445~455        |

1) high-quality piano wire, 2) wire breaking strength

### Cropping



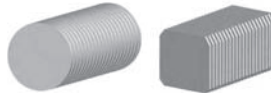
Single crystalline silicon ingot / Sapphire ingot

### Squaring



Single crystalline silicon ingot / Polycrystalline silicon jumbo-ingot / Sapphire ingot for cover glass brick

### Wafering



Mono-poly-silicon ingot wafer / Sapphire wafer / Sic wafer

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